

OFFICIAL
IN THE UNITED STATES PATENT & TRADEMARK OFFICE

Appln. Ser. No.:	Filed:	Inventor(s):	Atty Dkt:
09/074,012	5 May 1998	S. YOSHIDA et al.	114GI-121 (0694-121)

Title: High Thermal Conductivity Composite Magnetic Body

Examiner: B.D. Pianalto Art Unit: 1762

Asst. Comm'r for Patents
Washington, D.C. 20231-0001

11 Pages Total VIA FACSIMILE
703-872-9310

RESPONSE AND AMENDMENTS

Dear Sir:

In complete and timely response to the Office action mailed 4 December 2002, please first amend the application as shown by the mark-ups in the Appendix at the end of this paper, such amendments presenting the claims as follows:

IN THE CLAIMS:

10. (Fifth amendment.) An electronic device having attached thereto a stationary electromagnetic interference suppressing body for suppressing electromagnetic interference due to external and/or internal presence of electromagnetic waves, said stationary electromagnetic interference suppressing body being in the form of a sheet comprising an organic binding agent layer and a soft magnetic powder dispersed through said organic binding agent layer, wherein said stationary electromagnetic interference suppressing body further comprises a separate heat conductive but electrically insulative powder dispersed through said organic binding agent layer, for improving the thermal conductivity of said electromagnetic interference suppressing body during use thereof in association with said electronic device.

14. (Second amendment.) The electronic device of claim 13, wherein said electromagnetic interference suppressing body is in the form of a sheet, for use, in contact with components to control the temperature thereof during use of said